Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP X150 100G CFP2 LC LR4 10km SM Transceiver(JH289A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of CFP2-LR4 Module to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	1（for CFP2）
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver, small flatblade, Phillips, Torx, or hex as needed	
Pliers, needle nose or similar	
Tweezers, solder iron	

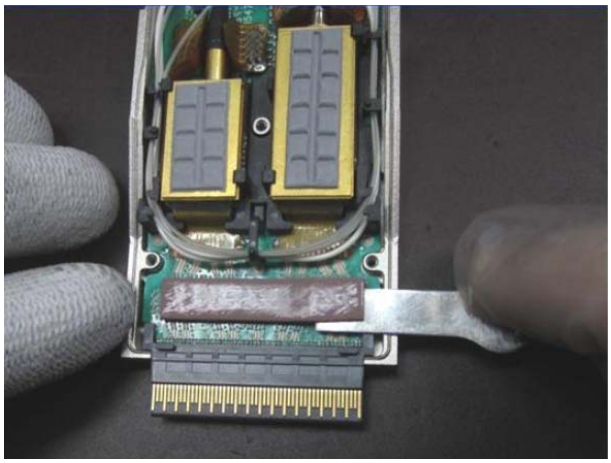
3.0 Product Disassembly Process

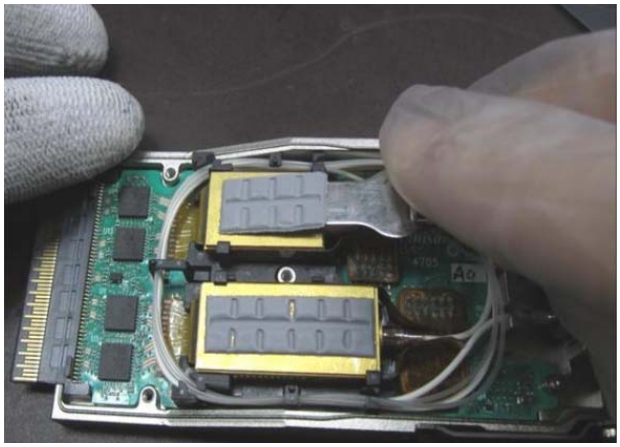
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Loose the screw in top housing by screwdriver
2. Open the housing
3. Desoldering the OSA with solder iron
4. Split OSA and PCBA

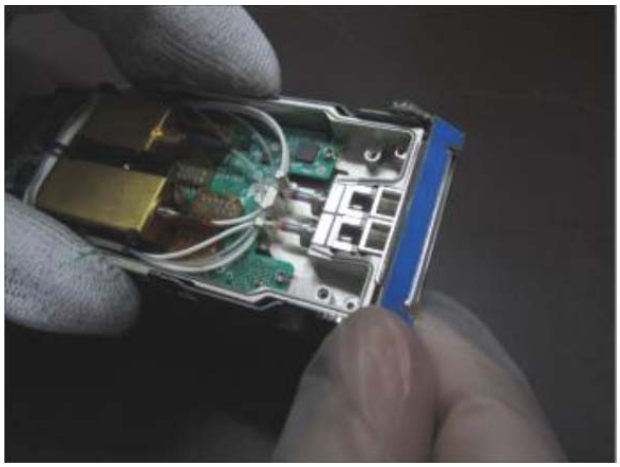
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. a) Place the module into the top screwing assembly fixture.
   b) Close the top opening of fixture.
   c) Unscrew all the 5 locations on top shell.
   d) Take out the screws and remove the top cover.

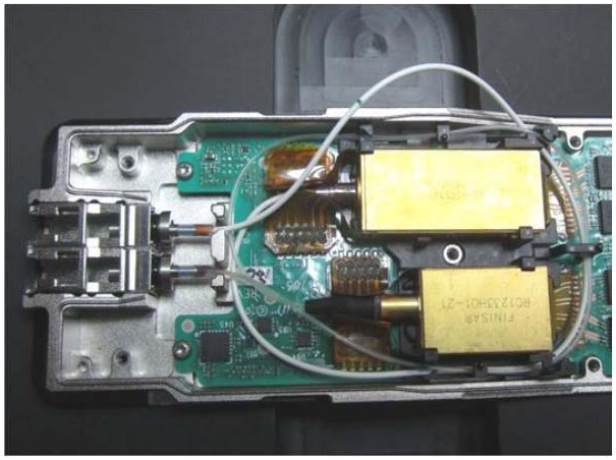


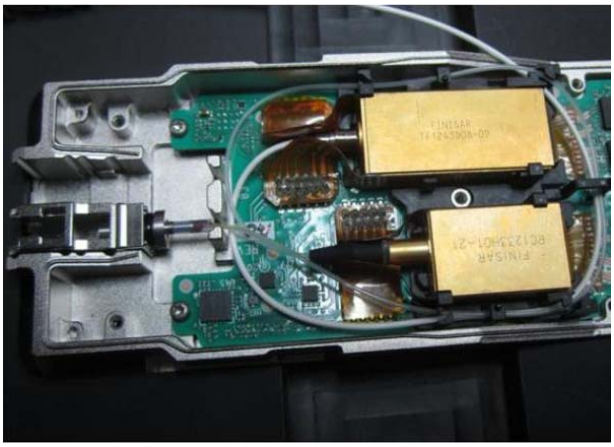


2. Remove thermal pads and fiber catch.

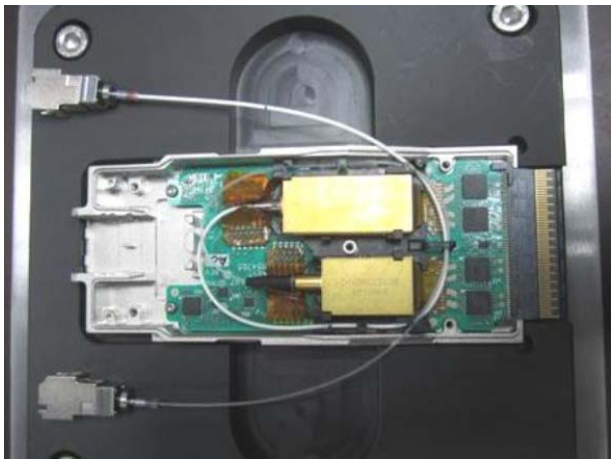


3. Remove the slider and bail.

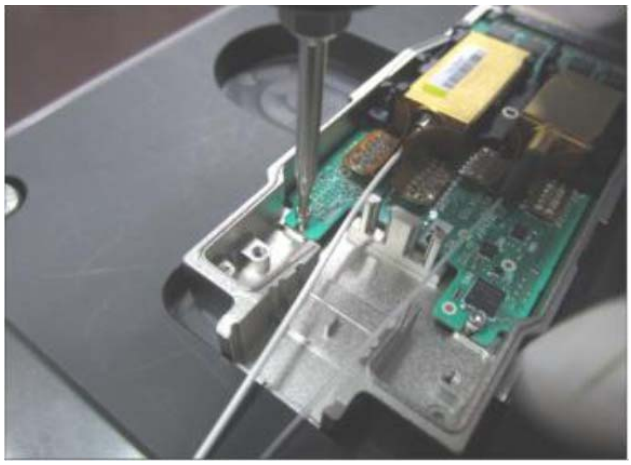




4. a) Place the module in PCBA to shell Asy fixture.
   b) Take out the fiber from OSA tray fiber track.
   c) Take out the TOSA block.



5. a) Repeat the previous steps for ROSA disassembly.
   b) Un-loop the TOSA and ROSA fiber from OSA tray.



6. a) Completely remove the fiber from the TOSA tray fiber track.
   b) Remove the two pcs screws from PCBA.

7. Place the PCBA into the carrier or in-process tray.

3.3Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details

4. Revised record

Date	Version	Author	Modify content
2015.07.30	V0	Guolei 11313	Initial version